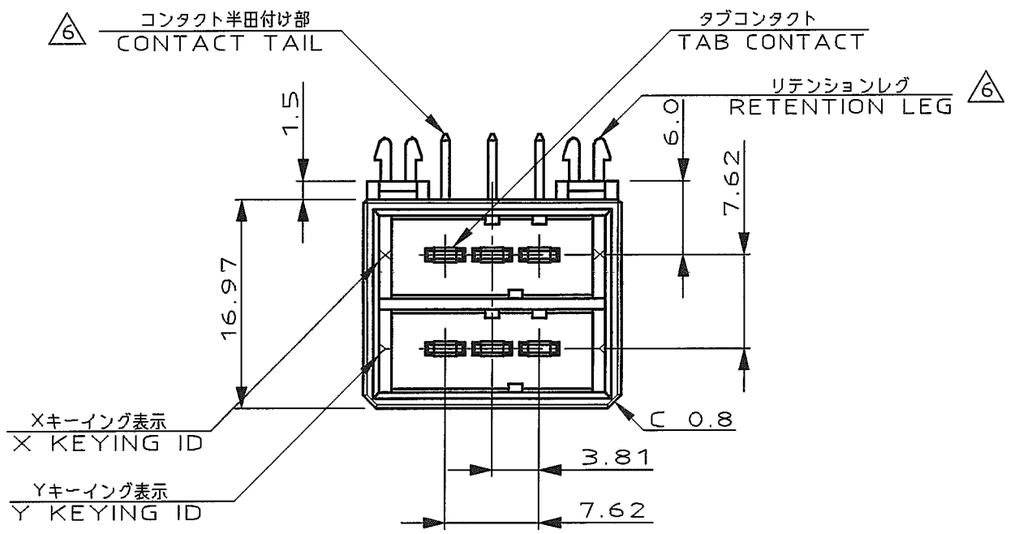
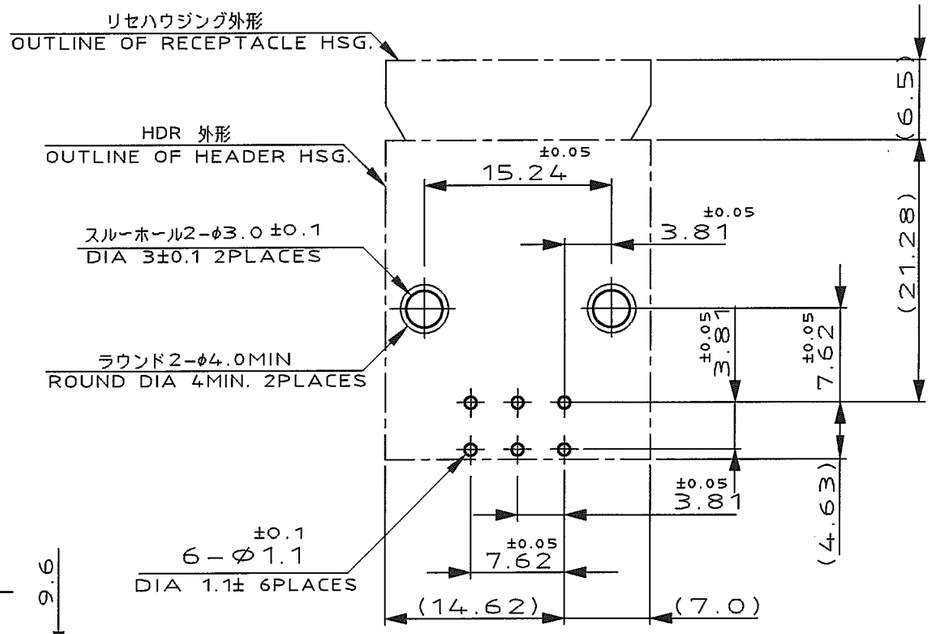
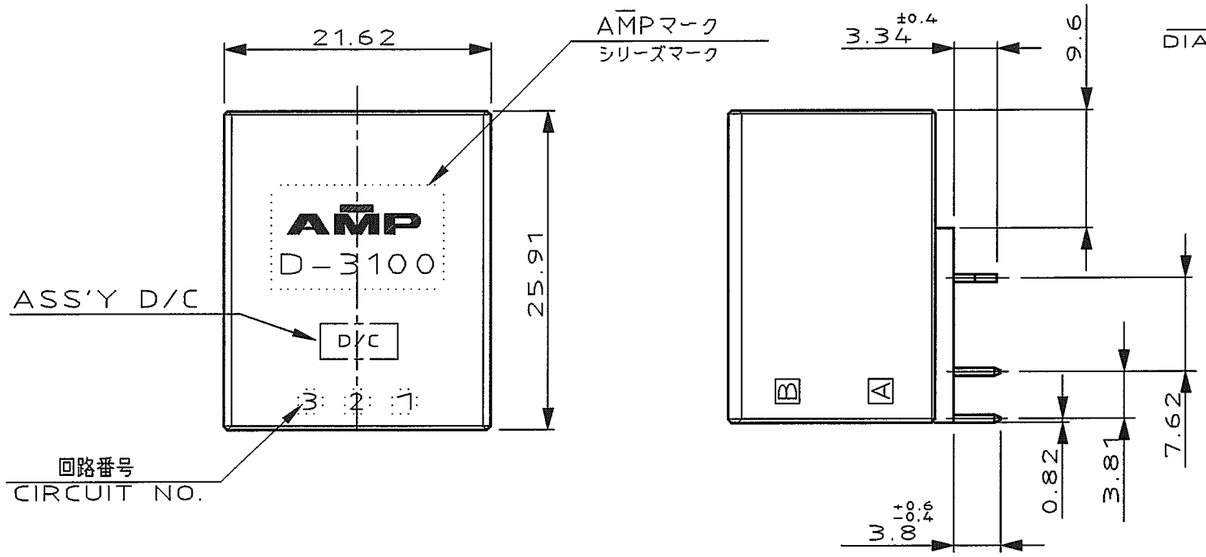
NUMBER 178137

3rd ANGLE PROJECTION

METRIC







（非累積公差）

推奨基板取付け穴寸法　（コネクタ搭載面）

RECOMEND PC BOARD HOLL PATTERN(NOT ACCUMLATE TOLERANCE)

PC BOARD THICKNEES;1.6±0.1 (PC 基板厚;1.6±0.1)

注記

1. 材料；ハウジング；ガラス入りポリエステル樹脂
   コンタクト；銅合金　熱可塑性ポリエステル樹脂
   リテンションレグ；銅合金
2. めっき：(コンタクト接触部)ニッケル下地の上に 0.38μMIN金メッキ
3. めっき：(コンタクト接触部)ニッケル下地の上に 0.76μMIN金メッキ
4. めっき：(コンタクト全面)ニッケル下地の上に 2.0 μMINスズメッキ
5. ~~(リテンションレグとコンタクト半田付け部)ニッケル下地の上に半田メッキ~~
6. めっき：リテンションレグとコンタクト半田付部
   ：ニッケル下地の上にスズめっき

NOTES

1. MATERIAL HOUSING:GLASS FILED POLYESTER
   CONTACT:COPPER ALLOY
   RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μMIN GOLD PLATED OVER NICKEL
3. FINISH(CONTACT AREA):0.76μMIN GOLD PLATED OVER NICKEL
4. FINISH(CONTACT):2.0 μMIN TIN PLATED OVER NICKEL
5. ~~FINISH(RETENTION LEG AND CONTACT TAIL).TIN-LEAD PLATED OVER NICKEL~~
6. FINISH(RETENTION LEG): TIN PLATED
   (CONTACT TAIL) OVER NICKEL

	XY	6 4	3-178137-5
		6 3	3-178137-3
		6 2	3-178137-2
	YY	6 4	2-178137-5
		6 3	2-178137-3
		6 2	2-178137-2
	XX	6 4	1-178137-5
		6 3	1-178137-3
		6 2	1-178137-2
KEYING LOCATION	KEYING NAME	FINISH	PART NO.

LTR	REVISION RECORD	DR	CHK	DATE
C1	REVISED PER ECO-11-005030	RK	HMR	24MAR11

TE Connectivity

WIRE RANGE mm² (AWG −)	INSULATION DIA − mmφ
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. 1-JULY-'92 Y.TANAKA	DE. 1-JULY-'92 Y.TANAKA
CHK. 6-JUL-'92 S.MANABE	APP. 6-JUL-'92 S.MANABE

NAME DYNAMIC D-3100 3.81 X 7.62 PITCH(H) 6POS. HDR CONN. ASS'Y (KEY;XX,YY,XY)

一般公差 (GENERAL TOLERANCE)
10未満 ±0.3
10未満 30以下 ±0.4
30未満100以下 ±0.45
角度 ±3°

SIZE	LOC	NUMBER
A3	J	C-178137
SCALE 2-1	REV. C1	SHEET 1 OF 1

(CUSTOMER DRAWING) 顧客用図面

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

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